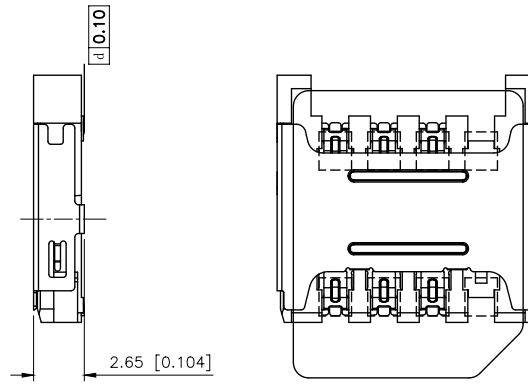
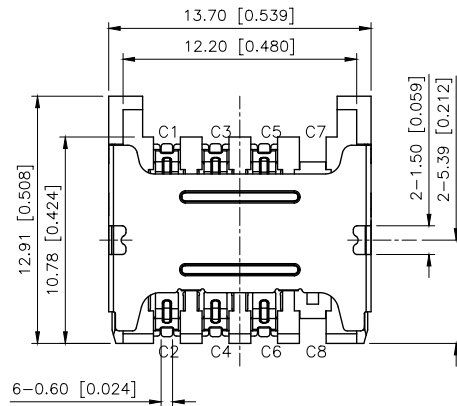
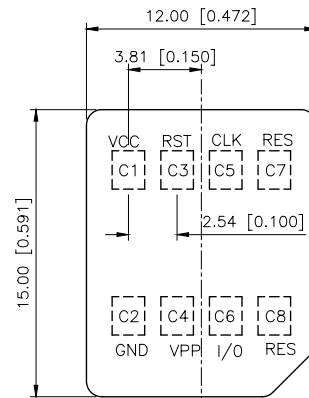
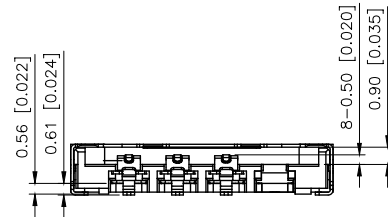


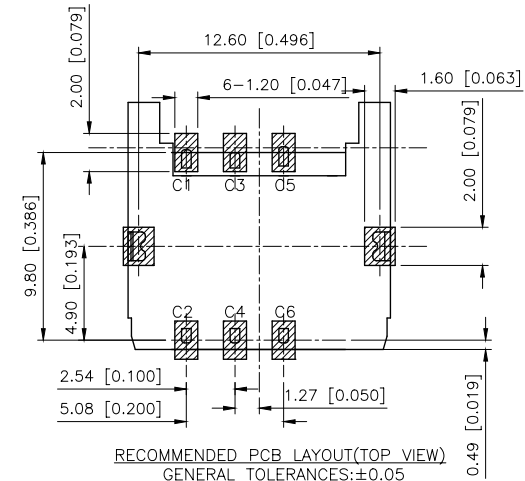
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.16	阿树



- NOTES:
- 1.MATERIAL:
HOUSING 胶壳:LCP UL 94V-0
CONTACT 端子:C5210R-H
SHELL 外壳:SUS201-H
- 2.FINISH 电镀:
CONTACT端子:GOLD FLASH PLATED ON CONTACT AREA:
GOLD FLASH PLATING ON SOLDER TAILS,
WITH ENTIRE CONTACT UNDERPLATED NICKEL
SHELL 外壳: NICKEL UNDERPLATED OVERALL.
GOLD FLASH PLATED ON SOLDER TAILS
- 3.ELECTRICAL CHARACTERISTICS 电气特性
RATING CURRENT 额定电流: 0.5A MAX.
CONTACT RESISTANCE 接触电阻:50 mΩ MAX
DIELECTRIC WITHSTANDING 耐电介质: 500V AC MIN.
INSULATION RESISTANCE 绝缘电阻:1000 MΩ MIN.
- 4.MECHANICAL CHARACTERISTICS 机械特性
MATING CYCLE 拔插周期:3000 CYCLES



MICRO SIM CARD
芯片面朝下焊接



MICRO SIM CARD	
PIN NO.	DESCRIPTION
C1	VCC
C3	RST
C5	CLK
C7	
C2	GND
C4	VPP
C6	I/O
C8	

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKSIM-2651-P6
APPROVED		SIZE: A4	DWG NO.: X-XKSIM-2651-P6
XKB INDUSTRIAL PRECISION CO.,LIMITED			SCALE N/A
			PAGE 1/1
			REVISION A1